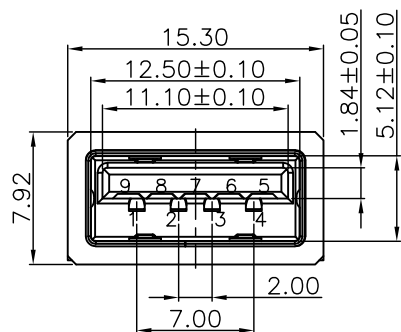


NOTE:

1.MATERIAL:

- 1.1 INSULATOR:PA10T UL94V-0,BLACK
- 1.2 CONTACT:C7025(T=0.25mm)
- 1.3 SHELL:SUS304 (T=0.30mm)

2.ELECTRICAL CHARACTERISTICS:

- 2.1 CONTACT RESISTANCE:30mΩ MAXIMUM
- 2.2 CONTACT CURRENT RATING:1.5A
- 2.3 DIELECTRIC WITHSTANDING VOLTAGE:500 V

R.M.S.

- 2.4 INSULATION RESISTANCE 1000 MEGOHMS MIN
- 2.5 OPERATING TEMPERATURE:-40°C ~ 85°C

3 MECHANICAL CHARACTERISTICS:

- 3.1 MATING FORCE:3.57kg MAX
- 3.2 UNMATED FORCE:1.02kg MIN
- 3.3 DURABILITY:MANDATORY:5,000 CYCLES

4.PLATING

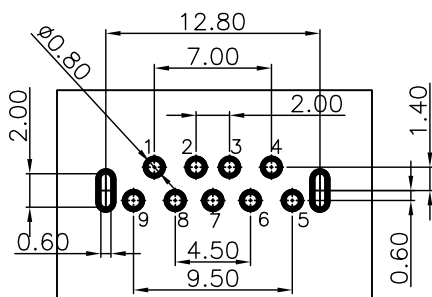
4.1 TERMINAL:

- 30u" MIN. Ni UNDERPLATED OVERALL
- 80u"MIN. Tin PLATED ON SOLDER AREA
- 1u" PLATED ON CONTACT AREA

4.2 SHELL:50u"MIN. Ni PLATED OVERALL

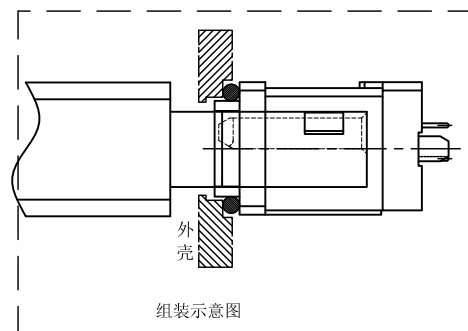
- 5.5.DESIGN FOR WATERPROOF WITH IPX7(WATER SLOT WITH 1.0MM&30MINUTES)

Pin #	SIGNAL NAME	DESCRIPTION
1	VBUS	POWER
2	D-	USB 2.0 DIFFERENTIAL PAIR
3	D+	
4	GND	GROUND FOR POWER RETURN
5	Std_SSRX-	SUPERSPEED RECEIVER DIFFERENTIAL PAIR
6	Std_SSRX+	
7	GND_DRAIN	GROUND FOR SIGNAL RETURN
8	Std_SSTX-	SUPERSPEED TRANSMITTER DIFFERENTIAL PAIR
9	Std_SSTX+	
Shell	Shield	CONNECTOR METAL SHELL



RECOMMENDED PCB LAYOUT(TOP VIEW)

THICKNESS T=1.2mm
DEFAULT TOLERANCE+/-0.05



4	Inner Shell	1	SUS 304 Ni 50U"	T=0.30mm
3	PLASTIC Shell	1	PA10T (G.F30%)	
2	Contact	9	C7025 Ni 50U" Au1U" Plating Solder area Sn 80-120U"	T=0.25mm
1	Housing	1	PA10T (G.F30%)	
ITEM	PART NAME	Q'TY	FINISH	NOTE



深圳市华宇创精密电子有限公司

TOLERANCE: X.X ±0.30 X.XX ±0.25 X.XXX ±0.15 X' ±2" X.X' ±0.5'	DRAWN BY : 陈一鸣	DATE : 2014-02-23	PART NAME: 防水USB 3.0 AF 180° DIP	
	CHECKED BY: 马跃	DATE : 2014-02-23	PART NO.	HYCW177-USBA09-140B
	APPROVED BY: 邱敏	DATE : 2014-02-23	MOLD NO.	
			DRAW NO:	HYC-2512081102
SCALE:1:1	SIZE: A4		SHEET NO.	1 OF 1